Electronic Supplementary Material (ESI) for Soft Matter.

Flexible and Electrically Conductive Composites based on 3D Hierarchical Silver Dendrites

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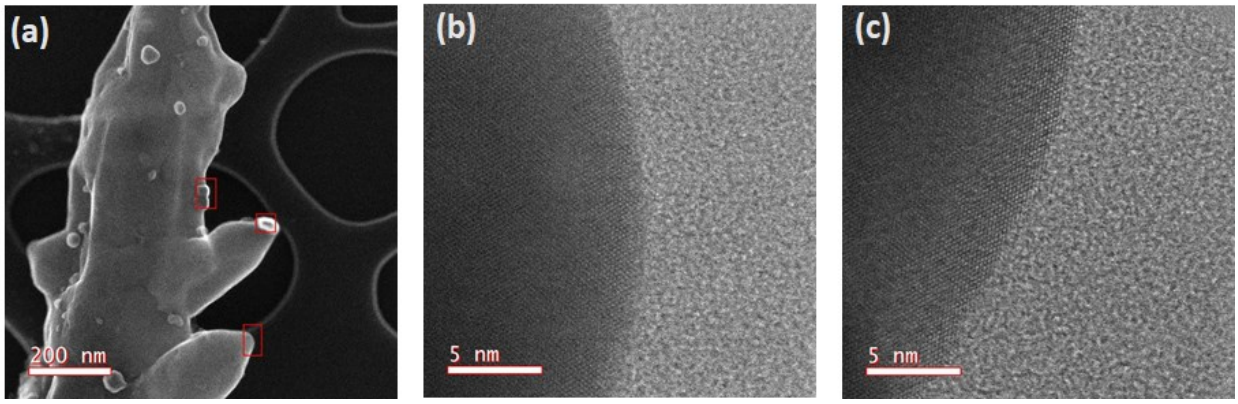

Fig. S1 (a) STEM image of a SD branch with red box indicating HR imaging locations; (b-c) HR STEM imaging at the rims of SD branches.

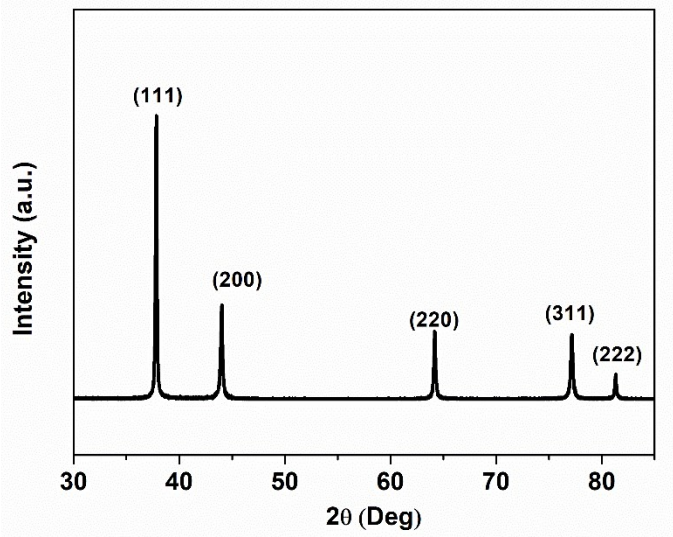

Fig. S2 XRD patterns of SD structures.

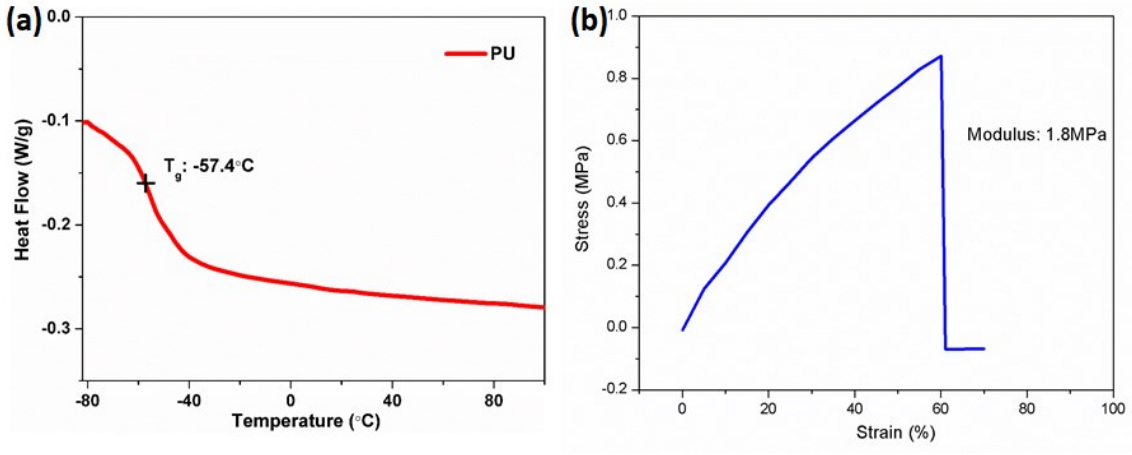

Fig. S3 (a) DSC curve and (b) stress-strain curves of the cured PU resin.

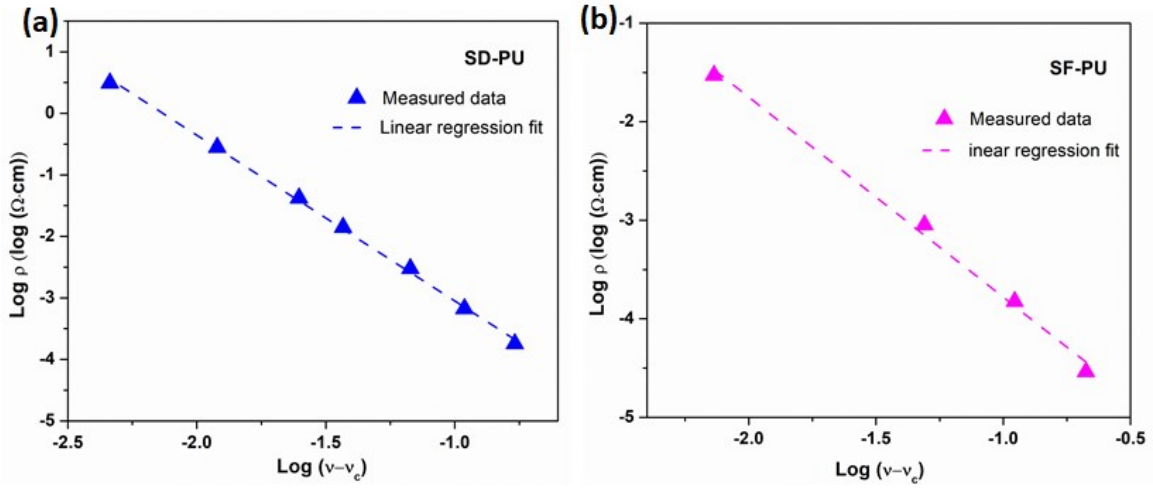

Fig. S4 Measured resistivity vs linear regression fitted resistivity data for (a) SD-PU and (b) SF-PU composites.

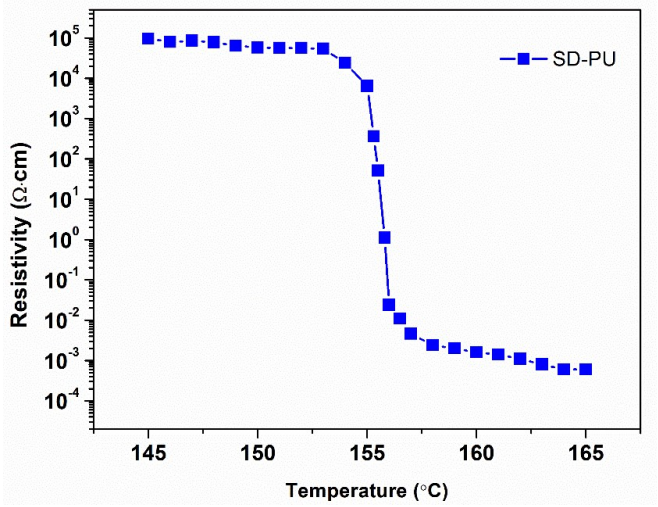

Fig. S5 Resistivity change of SD-PU film as a function of temperature in the course of curing reaction.